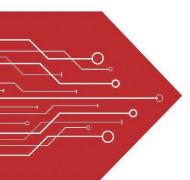
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

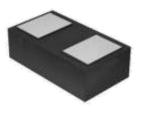
Product data sheet

www.msksemi.com

Features

Ultra Low Capacitance: 0.30pF(typ.)
Reverse Working Voltage: 5V
IEC 61000-4-2 (ESD Air): ±20kV
IEC 61000-4-2 (ESD Contact): ±20kV
IEC 61000-4-5 (Lightning 8/20µs): 5A

Pin Description



Applications

Smart Phone and Tablet PC TV and Set Top Box Wearable Devices PDA

Schematic Diagram



Limiting Values($T_A = 25$ °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
	Floatroatatia Disabarga Voltaga	IEC 61000-4-2; Contact Discharge	-	±20	kV
V _{ESD} Electrostatic Discharge Voltage	IEC 61000-4-2; Air Discharge	-	±20	kV	
P _{PP}	Peak Pulse Power	t _P = 8/20 μs	-	110	W
ІРРМ	Rated Peak Pulse Current	t _P = 8/20 μs	-	5.0	Α
T _A	Operating Temperature Range	-	-55	125	$^{\circ}\!\mathbb{C}$
T _{stg}	Storage Temperature Range	-	-55	150	$^{\circ}$

ESD5301N-MS



Electrical Characteristics(T_A = 25 °C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
V_{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	5.0	٧
V_{BR}	Breakdown Voltage	I _R = 1mA; T _A = 25 °C	6.0	8.5	9.5	V
I _R	Reverse Leakage Current	V _{RWM} = 5V; T _A = 25 °C	-	-	0.1	μA
Vc	Clamping Voltage	I _{PP} =1A, t _P =8/20μs	-	-	10	V
		I _{PP} =5.0A, t _P =8/20µs	-	-	22	V
Сл	Junction Capacitance	V _R = 0V, f = 1 MHz	-	0.30	0.40	pF

Typical Characteristics

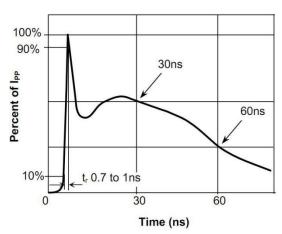


Fig.1 Pulse Waveform-ESD (IEC61000-4-2)

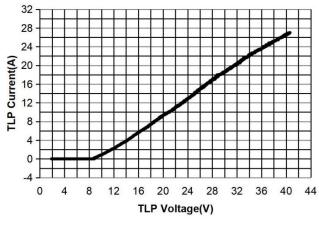


Fig.2 Transmission Line Pulse (TLP)

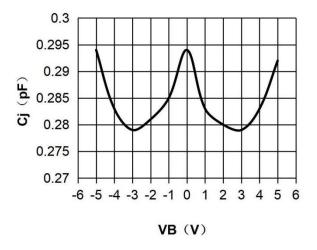


Fig.3 Capacitance vs. Reveres Voltage

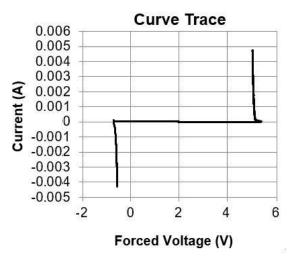
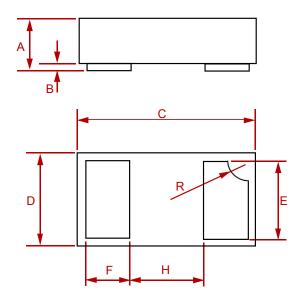


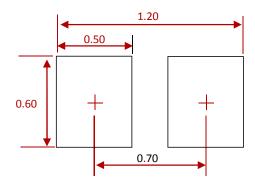
Fig.4 IV Curve





Dim	Inches		Millimeters		
	MIN	MAX	MIN	MAX	
Α	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40Тур.		
R	0.001	0.005	0.05	0.15	

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5301N-MS	DFN1006-2	10000



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